# **MP7636A**



15 V CMOS Microprocessor Compatible Double-Buffered, Multiplying 16-Bit Digital-to-Analog Converter

## **FEATURES**

- Four Quadrant Multiplication
- 16-Bit Monotonicity
- Lower Data Bus Feedthrough @ CS = 1
- Low Feedthrough Error
- Low Power Consumption
- TTL/5 V CMOS Compatible
- Double Buffered
- Decoded DAC Approach
- Latch-Up Free

### **BENEFITS**

- High Accuracy Performance at Low Cost
- Easy Interface with 8-Bit Microprocessors
- Simple Upgrade of MP1230A Family to High Accuracy (Pin Compatible)
- Reduced Board Space
- 16-Bit Bus Version: MP7626

#### GENERAL DESCRIPTION

The MP7636A is manufactured using advanced thin film resistors on a double metal CMOS process. The MP7636A incorporates a unique bit decoding technique yielding lower glitch, higher speed and excellent accuracy over temperature and time. 16-bit differential non-linearity is achieved with minimal laser trim.

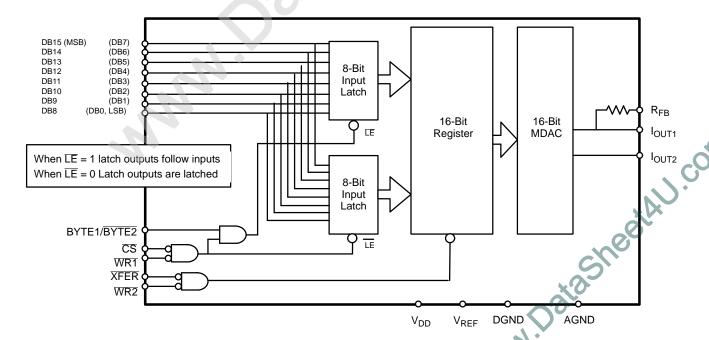
The MP7636A is packaged in a 20-pin 300 mil wide DIP and is a direct 16-bit replacement for the 12-bit DAC1230 series. Full

pin-for-pin compatibility allows existing systems to be upgraded to 16 bits without hardware modification.

The MP7636A provides 16-bit data loading through 8 input data lines for direct interface to 8-bit data buses. All data loading and data transfer operations are identical to the WRITE cycle of a static RAM.

The MP7636A uses a unique circuit which significantly reduces transients in the supplies during DATA bus transitions at  $\overline{\text{CS}}$  = 1.

## SIMPLIFIED BLOCK DIAGRAM





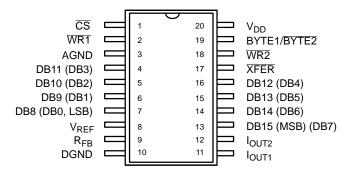
### ORDERING INFORMATION

Package Type	Temperature Range	Part No.	INL (LSB)	DNL (LSB)	Gain Error (% FSR)
SOIC	-40 to +85°C	MP7636AJS	<u>+</u> 4	<u>+</u> 4	0.1
SOIC	-40 to +85°C	MP7636AKS	<u>+</u> 2	<u>+</u> 2	0.1

<sup>\*</sup>Contact factory for non-compliant military processing

## **PIN CONFIGURATION**

See Packaging Section for Package Dimensions



20 Pin SOIC (Jedec, 0. 300") S20

## **PIN OUT DEFINITIONS**

PIN NO.	NAME	DESCRIPTION
1	CS	Chip Select (Active Low)
2	WR1	Write1 (Active Low)
3	AGND	Analog Ground
4	DB11 (DB3)	Data Input Bit 11 (MSB) Data Input Bit 3
5	DB10 (DB2)	Data Input Bit 10 Data Input Bit 2
6	DB9 (DB1)	Data Input Bit 9 Data Input Bit 1
7	DB8 (DB0)	Data Input Bit 8 Data Input Bit 0 (LSB)
8	$V_{REF}$	Reference Input Voltage
9	R <sub>FB</sub>	Internal Feedback Resistor
10	DGND	Digital Ground
11	I <sub>OUT1</sub>	Current Output 1

PIN NO.	NAME	DESCRIPTION
12	I <sub>OUT2</sub>	Current Output 2
13	DB15 (MSB) (DB7)	Data Input Bit 15 (Most Significant Bit) Data Input Bit 7
14	DB14 (DB6)	Data Input Bit 14 Data Input Bit 6
15	DB13 (DB5)	Data Input Bit 13 Data Input Bit 5
16	DB12 (DB4)	Data Input Bit 12 Data Input Bit 4
17	XFER	Transfer Control Signal (Active Low)
18	WR2	Write 2 (Active Low)
19	BYTE1/	Byte Sequence Control
	BYTE2	
20	$V_{DD}$	Power Supply





## **ELECTRICAL CHARACTERISTICS**

 $(V_{DD} = + 15 \text{ V}, V_{REF} = +10 \text{ V} \text{ unless otherwise noted})$ 

			25°C		Tmin to	Tmax		
Parameter	Symbol	Min	Тур	Max	Min	Max	Units	Test Conditions/Comments
STATIC PERFORMANCE <sup>1</sup>								FSR = Full Scale Range
Resolution (All Grades)	N	16			16		Bits	
Integral Non-Linearity (Relative Accuracy) J, S	INL			<u>+</u> 4		<u>+</u> 4	LSB	Best Fit Straight Line Spec. (Max INL – Min INL) / 2
K, L, T				<u>+</u> 2		<u>+</u> 2		
Differential Non-Linearity J, S K, T L	DNL			<u>+</u> 4 <u>+</u> 2 <u>+</u> 1		<u>+</u> 4 <u>+</u> 2 <u>+</u> 2	LSB	All grades guaranteed monotonic over full operating temperature range.
Gain Error	GE			<u>+</u> 0.1		<u>+</u> 0.1	% FSR	Using Internal R <sub>FB</sub>
Gain Temperature Coefficient <sup>2</sup>	TC <sub>GE</sub>					<u>+</u> 2	ppm/°C	$\Delta$ Gain/ $\Delta$ Temperature
Power Supply Rejection Ratio	PSRR			<u>+</u> 50		<u>+</u> 50	ppm/%	$ \Delta Gain/\Delta V_{DD} $ $\Delta V_{DD} = \pm 5\%$
Output Leakage Current	l <sub>OUT</sub>			<u>+</u> 10		<u>+</u> 200	nA	I <sub>OUT1</sub> only
DYNAMIC PERFORMANCE <sup>2</sup>								
Current Settling Time	t <sub>S</sub>		2				μs	To 1/2 LSB
AC Feedthrough at I <sub>OUT1</sub>	F <sub>T</sub>		2				mV p-p	$R_L$ =100 $\Omega$ , $C_{EXT}$ =13 $pF$ $V_{REF}$ = 20 $V$ $p$ - $p$ Sine wave @ 10 $kHz$
REFERENCE INPUT								
Input Resistance	R <sub>IN</sub>	2.5		7.5	2.5	7.5	kΩ	
LOGIC INPUTS <sup>3</sup>								
Input High Voltage Input Low Voltage Input Current Input Capacitance	V <sub>INH</sub> V <sub>INL</sub> I <sub>LKG</sub>	3.0	2.4	0.8 <u>+</u> 1	3.0	0.8 <u>+</u> 1	V V μΑ	
Data Control	C <sub>IN</sub> C <sub>IN</sub>		5 5				pF pF	
ANALOG OUTPUTS <sup>2</sup>								
Output Capacitance	C <sub>OUT1</sub> C <sub>OUT1</sub> C <sub>OUT2</sub> C <sub>OUT2</sub>			280 120 100 240			pF pF pF pF	DAC all 1's DAC all 0's DAC all 1's DAC all 0's



## **ELECTRICAL CHARACTERISTICS (CONT'D)**

Parameter	Symbol	Min	25°C Typ	Max	Tmin to Min	Tmax Max	Units	Test Conditions/Comments
POWER SUPPLY <sup>5</sup>								
Functional Voltage Range <sup>2</sup> Supply Current	V <sub>DD</sub> I <sub>DD</sub>	4.5		16.5 1	5.0	16.5 1	V mA	All digital inputs 0 V or V <sub>DD</sub>
SWITCHING CHARACTERISTICS <sup>2, 4</sup>								
CS to WR Set-Up Time CS to WR Hold Time Data Valid to WR Set-Up Time Data Valid to WR Hold Time WR, XFER Pulse Width	tcs tch t <sub>DS</sub> t <sub>DH</sub>	150 10 70 70 150					ns ns ns ns	

#### NOTES:

- (1) Full Scale Range (FSR) is 10V for unipolar mode.
- (2) Guaranteed but not production tested.
- (3) Digital input levels should not go below ground or exceed the positive supply voltage, otherwise damage may occur.
- (4) See timing diagram.
- (5) Specified values guarantee functionality. Refer to other parameters for accuracy.

Specifications are subject to change without notice

# ABSOLUTE MAXIMUM RATINGS (TA = +25°C unless otherwise noted)<sup>1, 2, 3</sup>

Voltage at Any Digital Input GND –0.5 to V <sub>DD</sub> +0.5 V	AGND to DGND±1 \ (Functionality Guaranteed +0.5 V)
Voltage at V <sub>REF</sub> Input <u>±</u> 25 V	Storage Temperature Range –65°C to 150°C
DC Voltage Applied to $I_{OUT1}$ or $I_{OUT2}$ GND $-0.5$ V to +17 V	Package Power Dissipation Rating to 75°C SOIC 900mW
Supply Voltage (V <sub>DD</sub> ) +17 V <sub>DC</sub>	Derates above 75°C 12mW/°C

## NOTES:

- Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
- conditions for extended periods may affect device reliability.

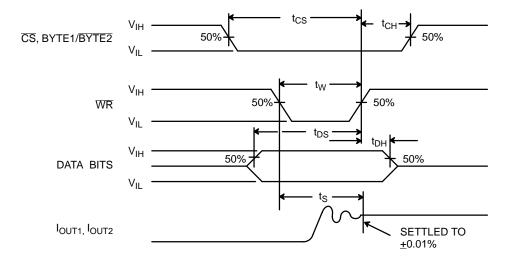
  Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. *All inputs have protection diodes* which will protect the device from short transients outside the supplies of less than 100mA for less than 100µs.
- 3 GND refers to AGND and DGND.

APPLICATION NOTES
Refer to Section 8 for Applications Information





## **TIMING DIAGRAM**



## **DEFINITION OF CONTROL SIGNALS:**

CS: Chip Select (Active low).

It will enable WR1.

WR1: Write 1 (Active low)

The WR1 is used to load the digital data bits (DB) into

the input latch.

BYTE1/BYTE2: Byte sequence control.

The BYTE1/BYTE2 control pin is used to select MSB

and LSB both input latches.

WR2: Write 2 (Active low).

It will enable XFER.

XFER: Transfer control signal (Active low).

This signal, in combination with  $\overline{WR2}$ , causes the 16-bit data which is available in the input latches to

transfer to the DAC register.

DB0 to DB15: Digital Inputs.

DB0 is the least significant digital input (LSB) and DB15 is the most significant digital input (MSB).

I<sub>OUT1</sub>: DAC Current Output 1 Bus.

 $I_{OUT1}$  is a maximum for a digital code of all 1's in the DAC register, and is zero for all 0's in the DAC register.

I<sub>OUT2</sub>: DAC Current Output 2 Bus.

 $I_{\mbox{\scriptsize OUT2}}$  is a complement of  $I_{\mbox{\scriptsize OUT1}}.$  The ladder termina-

tion has been tied to IOUT2 internally.

R<sub>FB</sub>: Feedback Resistor.

This internal feedback resistor should always be used (not an external resistor) since it matches the resistors in the DAC and tracks these resistor over temperature.

V<sub>REF</sub>: Reference Voltage Input.

This input connects an external precision voltage source to the internal DAC. The  $V_{REF}$  can be selected over the range of +25V to -25V or the analog signal for

a 4-quadrant multiplying mode application.

V<sub>DD</sub>: Power Supply Voltage.

This is the power supply pin for the part. The  $V_{DD}$  can be from +5 V DC to +15 V DC, however optimum volt-

age is +15 V DC.

AGND: Analog Ground.

Back gate of the DAC N-channel current steering

switches.

DGND: Digital Ground.

The timing diagrams for updating the DAC register are shown in *Figures 1* and *2*.





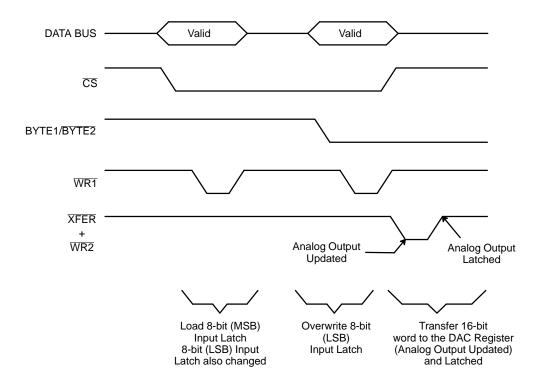


Figure 1. Typical Interface with an 8-bit Data Bus

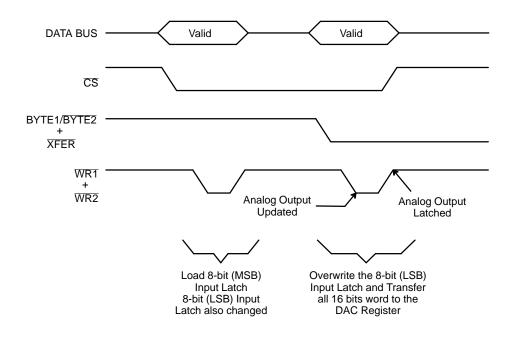
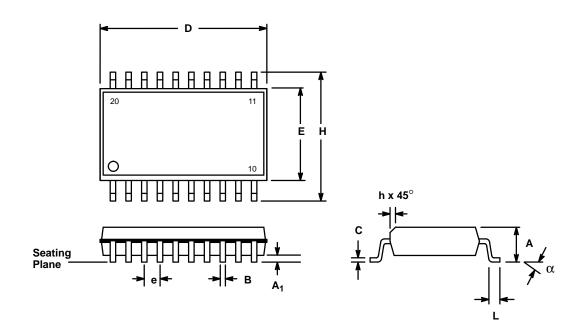


Figure 2. Automatic Transfer



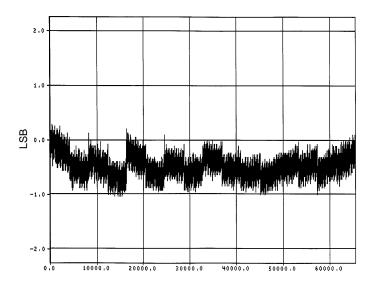
## 20 LEAD SMALL OUTLINE (300 MIL JEDEC SOIC) S20



	INC	CHES	MILLIN	METERS
SYMBOL	MIN	MAX	MIN	MAX
А	0.097	0.104	2.464	2.642
A <sub>1</sub>	0.0050	0.0115	0.127	0.292
В	0.014	0.019	0.356	0.483
С	0.0091	0.0125	0.231	0.318
D	0.500	0.510	12.70	12.95
Е	0.292	0.299	7.42	7.59
е	0.0	50 BSC	1.2	7 BSC
Н	0.400	0.410	10.16	10.41
h	0.010	0.016	0.254	0.406
L	0.016	0.035	0.406	0.889
α	0°	8°	0°	8°



## PERFORMANCE CHARACTERISTICS



Graph 1. Relative Accuracy vs. Digital Code

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